IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier	r Information													
ompany	name*	Company unique ID			J	Unique ID Authority				Response Date*				
nsemi											2024-04-16			
Contact Na	ame	Title - Contact			F	Phone - Contact*			Email	Email - Contact*				
roduct-E	Env-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized	d Representative*	Title - Representative			F	Phone - Representative*			Email	Email - Representative*				
roduct-E	Env-Stewards	Product Enviro Compliance]	NA			Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mi		Ifr Item Number Mfr Item Name				Effective Date	Version	Manufacturing S	Manufacturing Site		UOM	Unit Type	
		FSBB30CH60CT SPM3V_V4 INV		500V 30A LC		2024-04-16 CPA			17342.395	mg	Each			
	cturing Process Informa		Famminal Daga	Aller	-STD-020 MS	I. Dating	Dools Duo oo	as Dody Tampa	watura May Time at	Dook Tompo	Martine Number	n of Doflow Cv	olog	
	, , , , , , , , , , , , , , , , , , ,		Terminal Base Alloy J-STD-02 CU Alloy NA			L Kaung		Peak Process Body Temperature Max Time at Pea 0 C 30		· ·	k Temperature Number of Reflow Cycles seconds 3			
	Matte Tin (Sn) - annealed		OU AHOY		(A		ĮΨ		30	sec	onus [3			
omments														
	information regarding materia		•											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	67.7	mg	Supplier	Silicon (Si)	7440-21-3		67.7	mg
Die Attach	31.399	mg	Supplier	Silver (Ag)	7440-22-4		0.942	mg
			Supplier	Tin (Sn)	7440-31-5		30.3	mg
			Supplier	Copper (Cu)	7440-50-8		0.157	mg
Die Attach Epoxy	0.495	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0148	mg
			Supplier	Miscellaneous	Trade Secret		0.0247	mg
			Supplier	Silver (Ag)	7440-22-4		0.4208	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0346	mg
Die Attach Solder	9.701	mg	Supplier	Silver (Ag)	7440-22-4		0.2425	mg
			A	Lead (Pb)	7439-92-1	7a	8.9734	mg
			Supplier	Tin (Sn)	7440-31-5		0.4851	mg
Heat Sink	2720.0	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		979.2	mg
			Supplier	Copper (Cu)	7440-50-8		1740.7999	mg
Lead Frame	4318.38	mg	Supplier	Silver (Ag)	7440-22-4		1.47	mg
			Supplier	Iron (Fe)	7439-89-6		5.18	mg
			Supplier	Copper (Cu)	7440-50-8		4309.998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.73	mg
Mold Compound-Black	10122.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		606.0001	mg
			Supplier	Carbon Black (C)	1333-86-4		101.22	mg
			Supplier	Silica (SiO2)	14464-46-1		8808.7822	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		605.9981	mg
Plating	53.3	mg	Supplier	Tin (Sn)	7440-31-5		53.3	mg
Wire Bond - Al	18.3	mg	Supplier	Aluminum (Al)	7429-90-5		18.3	mg
Wire Bond - Cu	1.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.0224	mg
			Supplier	Copper (Cu)	7440-50-8		1.0976	mg